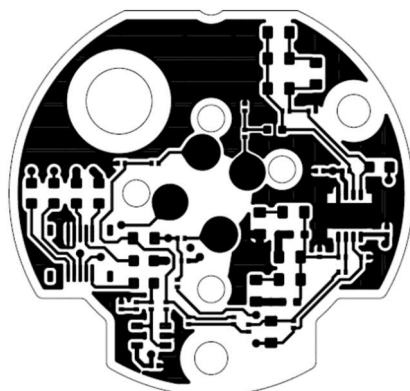
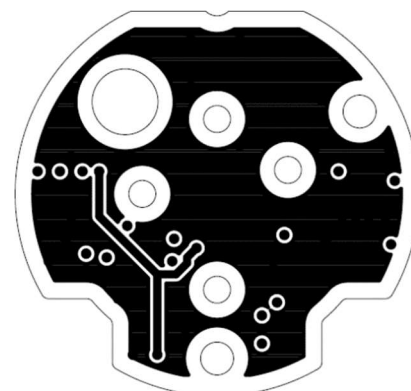


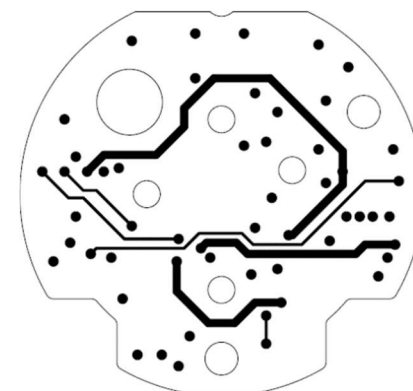
SILK PRINT FOR
PARTS SIDE



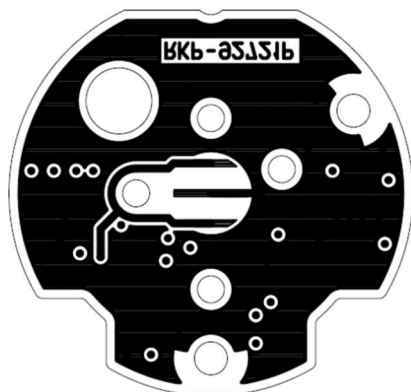
PARTS SIDE



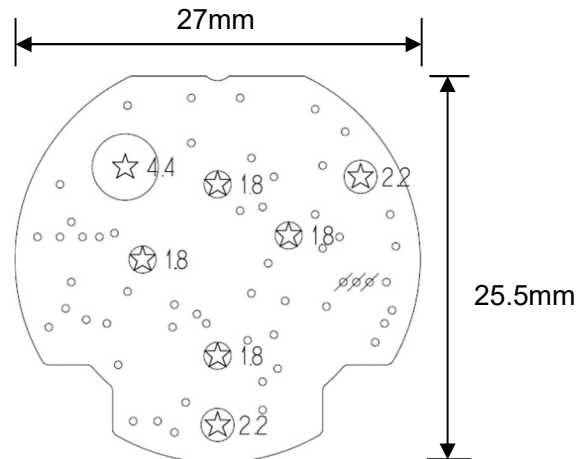
INNER LAYER
(2 LAYER)



INNER LAYER
(3 LAYER)



SOLDERING SIDE



THROUGH HOLE

MARK	DIAGRAM	HOLE
○	φ0.25	TH
/	φ0.25	TH
☆1.8	φ1.8	NTH
☆2.2	φ2.2	NTH
☆4.4	φ4.4	NTH

All drawings are view of parts side
SCALE 2:1

SPECIFICATION FOR PCB

- PCB No. : RKP-92721P
- Material : Glass epoxy
- Thickness : 1.2mm
- Layer number : 4
- Thickness copper film
Surface : 35um, Inner : 35um
- Copper thickness of the via's : 35um above.
- Minimum conductor width : 0.15mm
- CTI : 100 above.

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名 称 NAME SENSOR PCB FOR MODEL ESF
改版回数 REV.	0	総頁数 PAGES	1	
承認 APPROVED	検 討 CHECKED	製 図 DRAWN	作成日 DATE	図 番 DWG. NO.
北村正英	小野圭	秋山友	2020. 10. 15	E 4 - 6 9 9 1 - 6 1 3 9 - 2 0 - 0 1 A
RIKEN KEIKI 理研計測株式会社 機密情報 / CONFIDENTIAL				